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MIYAMOTO et al.(10) **Pub. No.: US 2023/0230863 A1**(43) **Pub. Date: Jul. 20, 2023**(54) **SUBSTRATE CONVEYANCE METHOD,
SUBSTRATE PROCESSING DEVICE, AND
RECORDING MEDIUM****Publication Classification**(51) **Int. Cl.**
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A substrate conveyance method, a substrate processing device, and a recording medium are provided. The substrate conveyance method includes: conveying a substrate into a receiving unit and confirming that the substrate is present in the receiving unit by detecting that light irradiated from an optical sensor is blocked by the substrate conveyed to the receiving unit; and stopping light irradiation from the optical sensor before the substrate is conveyed out from the receiving unit.

